

1c872 U.S. PTO
10/054001
01/19/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10054001	FILING DATE 01/19/2002	CLASS 257	SUBCLASS 2841	GAU 2841	EXAMINER
**APPLICANTS: Lin Mou-Shiung; Lee Jin-Yuan; Huang Ching-Cheng;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB DO NOT PUBLISH <input checked="" type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO MEG01-013	
TITLE : Thin film semiconductor package and method of fabrication					

U.S. DEPT. OF COMM /PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.				

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)